

MECHANICAL CASE OUTLINE

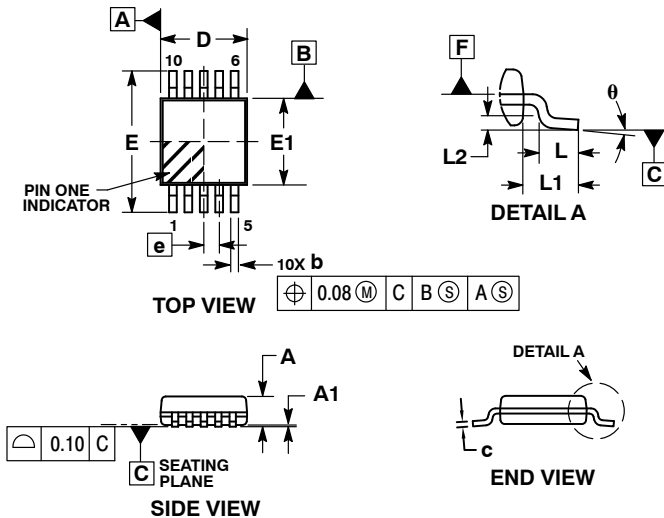
PACKAGE DIMENSIONS



SCALE 1:1

MSOP10, 3x3
CASE 846AE
ISSUE A

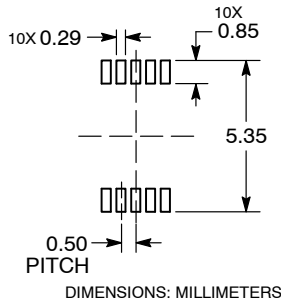
DATE 20 JUN 2017



- NOTES:
- DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
 - CONTROLLING DIMENSIONS: MILLIMETERS.
 - DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10 MM IN EXCESS OF MAXIMUM MATERIAL CONDITION.
 - DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 MM PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
 - DATUMS A AND B TO BE DETERMINED AT DATUM F.
 - A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

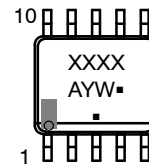
DIM	MILLIMETERS		
	MIN	NOM	MAX
A	---	---	1.10
A1	0.00	0.05	0.15
A2	0.75	0.85	0.95
b	0.17	---	0.27
c	0.13	---	0.23
D	2.90	3.00	3.10
E	4.75	4.90	5.05
E1	2.90	3.00	3.10
e	0.50 BSC		
L	0.40	0.70	0.80
L1	0.95 REF		
L2	0.25 BSC		
θ	0°	---	8°

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present and may be in either location. Some products may not follow the Generic Marking.

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